

**What is claimed is:**

1. A printed wiring board, comprising:

a plurality of spaced a part circuit layers, at least two of said layers being electrically  
5 connected by a blind hole/via wherein

a surface contact pad is formed by depositing over said blind hole/via an electrically  
conductive metallic layer.

2. A method of manufacturing a printed wiring board, comprising the steps of:-

10 providing a printed wiring board with a plurality of spaced a part conductor layers, at  
least two of said layers being electrically connected by a blind hole/via; and

forming a surface contact pad by depositing an electroconductive metallic layer  
over said blind hole/via.

15 3. A method as claimed in claim 2, wherein the step of forming the surface  
contact pad comprises plating an upper surface of said blind hole/via.